

ThinFlex

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ThinFlex-A Adhesiveless Double Sided Copper Clad Laminate (Halogen Free)

ThinFlex-A is an adhesiveless double sided (D/S) metal clad polyimide film, furnished in the form of roll laminate with RA or ED copper on both sides. ThinFlex-A adhesiveless D/S composites are designed for a wide variety of flexible circuit applications which require advanced material performance, temperature resistance, fine pitch, and high reliability.

1. Product Characteristics:

- * Excellent dimensional stability
- * Excellent flexibility
- * Finer line etch ability
- * Low moisture absorption
- * Excellent flammability (Flame class UL 94V-0; UL File No. E219724)
- * Excellent chemical resistance
- * Excellent thermal, mechanical, and electrical properties

2. Specifications:



*Other thicknesses and dimensions are available on customers' demand.

Technical Data Sheet: A-Rev.1, July/2006



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3. Construction:

Copper foil

Polyimide film

Copper foil

4. Properties:

Test item			Units	A-1003RD A-1005RD	A-1002ED A-1003ED A-1010ED	A-1005ED A-1010RD	Test Method	
Mechanical Properties	Peel Strength	As Received		≧ 0.80	≧ 1.00	≧ 1.20	IPC-TM650 2.4.9	
		Solder Float	Kgf/cm	≧ 0.80	≧ 1.00	≧ 1.20		
		After Temp. Cycling		≧ 0.80	≧ 1.00	≧ 1.20		
		Chemical Resistance		≧ 0.80	≧ 1.00	≧ 1.20	IPC-TM650 2.3.2	
	Flexural Endurance	M.D.	Times	≧300	≧300	≧300	JIS-C 6471 0.8mmR, 0.5kg	
		T.D.		≧300	≧300	≧300		
Electrical Properties	Surface Resistance		Ω	\geq 1.0x10 ¹¹	\geq 1.0×10 ¹¹	$\ge 1.0 \times 10^{11}$		
	Volume Resistance		Ω -cm	\geq 1.0x10 ¹²	\geq 1.0×10 ¹²	\geq 1.0×10 ¹²		
	Insulation Resistance		Ω	\ge 1.0x10 ⁹	\ge 1.0 \times 10 ⁹	\ge 1.0 \times 10 ⁹	IPC-TM650 2.6.3.2	
Physical and Thermal Properties	Dimensional Stability	M.D.	0.4.0.4		04.04	IPC-TM650		
		T.D.	%	-0.1~0.1	-0.1~0.1	-0.1~0.1	2.2.4C	
	Solder Float 10sec at 288℃ (550⁰F)			Pass	Pass	Pass	IPC-TM650 2.4.13	
	Thickness Tolerance		%	±10%	±10%	±10%	ThinFlex	
	lon Migration (1000hr/85%/85℃/50VDC)			Pass	Pass	Pass		
	UL Flame Class			94V-0	94V-0	94V-0	UL	

* Above data are typical values, and are not guaranteed values.

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Test item			Units	A-2002ED A-2003RD A-2005RD	A-2010RD A-2010ED	Test Method
Mechanical Properties	Peel Strength	As Received		≧ 0.80	≧ 1.00	IPC-TM650 2.4.9
		Solder Float	Kgf/cm	≧ 0.80	≧ 1.00	
		After Temp. Cycling		≧ 0.80	≧ 1.00	
		Chemical Resistance		≧ 0.80	≧ 1.00	IPC-TM650 2.3.2
	Flexural Endurance	M.D.	Times	N/A	N/A	JIS-C 6471 0.8mmR, 0.5kg
		T.D.		N/A	N/A	
Electrical Properties	Surface Resistance		Ω	$\ge 1.0 \times 10^{11}$	$\ge 1.0 \times 10^{11}$	IPC-TM650
	Volume Resistance		Ω -cm	$\ge 1.0 \times 10^{12}$	$\ge 1.0 \times 10^{12}$	2.5.17
	Insulation Resistance		Ω	\ge 1.0 \times 10 ⁹	\ge 1.0 \times 10 ⁹	IPC-TM650 2.6.3.2
Physical and Thermal Properties	Dimensional Stability	M.D.	%	-0.1~0.1	-0.1~0.1	IPC-TM650 2.2.4C
		T.D.				
	Solder Float 10sec at 288°C (550⁰F)			Pass	Pass	IPC-TM650 2.4.13
	Thickness Tolerance		%	±10%	±10%	ThinFlex
	lon Migration (1000hr/85%/85℃/50VDC)			Pass	Pass	
	UL Flame Class			94V-0	94V-0	UL

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Test item			Units	A-2003ED A-2005ED	A-2020RD A-2020ED	Test Method
Mechanical Properties	Peel Strength	As Received		≧ 1.20	≧ 2.00	IPC-TM650 2.4.9
		Solder Float	Kgf/c m	≧ 1.20	≧ 2.00	
		After Temp. Cycling		≧ 1.20	≧ 2.00	
		Chemical Resistance		≧ 1.20	≧ 2.00	IPC-TM650 2.3.2
	Flexural Endurance	M.D.	Times	N/A	N/A	JIS-C 6471 0.8mmR, 0.5kg
		T.D.		N/A	N/A	
Electrical Properties	Surface Resistance		Ω	$\geq 1.0 \times 10^{1}$	$\geq 1.0 \times 10^{1}$	IPC-TM650 2.5.17
	Volume Resistance		Ω -cm	$\ge 1.0 \times 10^{1}$	$\ge 1.0 \times 10^{1}$	
	Insulation Resistance		Ω	\ge 1.0 \times 10 ⁹	\ge 1.0 \times 10 ⁹	IPC-TM650 2.6.3.2
Physical and Thermal Properties	Dimensional	M.D.		-0.1~0.1	-0.1~0.1	IPC-TM650 2.2.4C
	Stability	T.D.	%			
	Solder Float 10sec at 288℃ (550⁰F)			Pass	Pass	IPC-TM650 2.4.13
	Thickness Tolerance		%	±10%	±10%	ThinFlex
	lon Migration (1000hr/85%/85℃/50VDC)			Pass	Pass	
	UL Flame Class			94V-0	94V-0	UL

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5. Storage:

ThinFlex-A will meet its shelf-life for at least 12 months after arrival at the user's factory when stored in the original packaging at temperatures of below 25°C and below 70% humidity. The products do not need refrigeration and should not be frozen.

Note: The information and data contained in this technical literature is believed to be accurate and is offered in good faith for the benefit of the user. The user should make his own tests to verify the suitability of this product for any application before its use. All data are typical values only and subject to change without notice.

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